

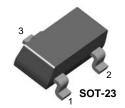
June 2007

BSR18B

PNP General Purpose Amplifier

This device is designed as a general purpose amplifier and switch.

Sourced from Process 23.



1. Base 2. Emitter 3. Collector



Absolute Maximum Ratings ${}^{\star}T_a = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage	40	V
V _{CEO}	Collector-Emitter Voltage	40	V
V _{EBO}	Emitter-Base Voltage	5.0	V
I _C	Collector Current (DC)	200	mA
T _{J,} T _{STG}	Junction Temperature, Storage Temperature	-55 ~ + 150	°C

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES

Thermal Characteristics *T_a = 25°C unless otherwise noted

Symbol	Characteristic	Max	Units
PD	Total Device Dissipation	230	mW
	Derate above 25°C	1.84	mW/°C
R Θ JA	Thermal Resistance, Junction to Ambient	550	°C/W

^{*}Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06".

¹⁾ These ratings are based on a maximum junction temperature of 150 degrees C.

²⁾ These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics * T_a = 25°C unless otherwise noted

Symbol	Parameter	Test Condition	MIN	MAX	Units
Off Charac	teristics				
V _(BR) CEO	Collector-Emitter Breakdown Voltage	Ic = 1.0 mA, I _B = 0	40		V
V _{(BR)CBO}	Collector-Base Breakdown Voltage	$Ic = 10 \mu A, IE = 0$	40		V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$IE = 10 \mu A, Ic = 0$	5.0		V
Ісво	Collector-Cutoff Current	VcB = 30 V		50	nA
І ЕВО	Emitter-Cutoff Current	Vce = 30 V, Veb = 3.0 V		50	nA

On Characteristics

hfE		Ic = 0.1 mA, VcE = 1.0 V Ic = 1.0 mA, VcE = 1.0 V Ic = 10 mA, VcE = 1.0 V Ic = 50 mA, VcE = 1.0 V Ic = 100 mA, VcE = 1.0 V	60 80 110 60 30	220	
VcE(sat)	Collector-Emitter Saturation Voltage *	Ic = 10 mA, I _B = 1.0 mA Ic = 50 mA, I _B = 5.0 mA		0.25 0.4	V V
V _{BE} (sat)	Emitter-Base Breakdown Voltage *	Ic = 10 mA, I _B = 1.0 mA Ic = 50 mA, I _B = 5.0 mA	0.65	0.85 0.95	V V

Small Signal Characteristics

Ccb	Collector-Base Capacitance	$V_{CB} = 5.0 \text{ V}, I_E = 0, f = 100 \text{ kHz}$	4.5	pF
Ceb	Emitter-Base Capacitance	V _{EB} = 0.5 V, I _C = 0, f = 100 kHz	10	pF

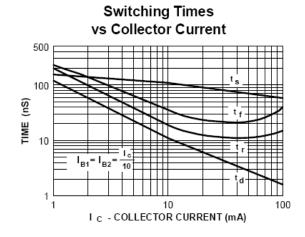
Switching Characteristics

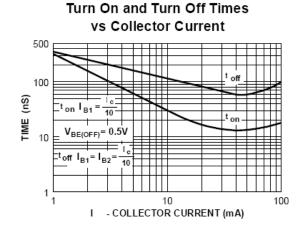
td	Delay Time	Ic = 10 mA, I _{B1} = 1.0 mA,V _{cc} = 3.0 V	35	ns
tr	Rise Time		35	pF
ts	Storage Time	Ic = 10 mA, IBon = IBoff = 1.0 mA	225	ns
tf	Fall Time	Vcc= 3.0 V	75	ns

^{*} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%

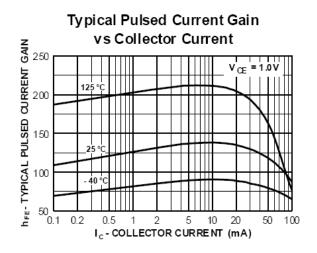
NOTE: All voltages (V) and currents (A) are negative polarity for PNP transistors.

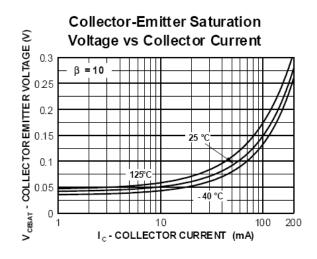
Typical Performance Characteristics

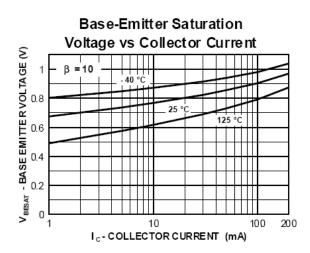


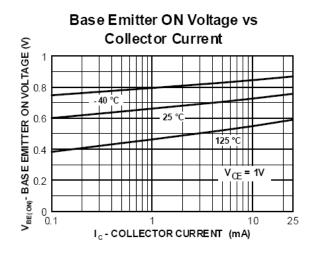


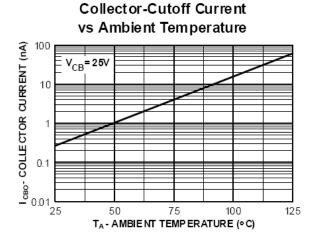
Typical Performance Characteristics (continued)

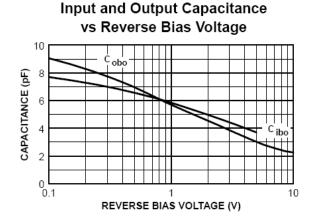












Common-Base Open Circuit





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